

GSMDD0903

100V P-Channel MOSFETs

Product Description

These P-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode.

These devices are well suited for high efficiency fast switching applications.

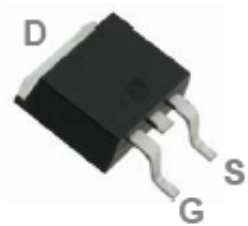
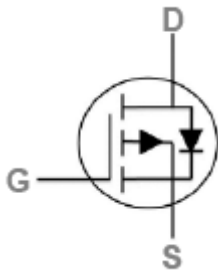
Features

- -100V, -10A, $R_{DS(ON)}=140m\Omega@V_{GS}=-10V$
- V_{GS} Guaranteed $\pm 25V$
- Improved dv/dt capability
- Fast switching
- Green Device Available
- TO-252-2L package design

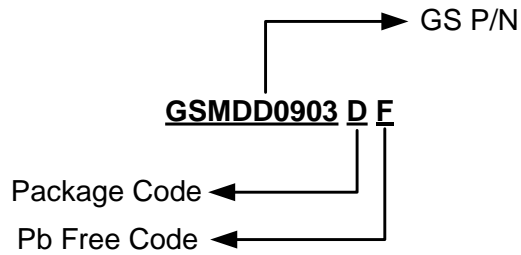
Applications

- Networking
- Load Switch
- LED applications

Packages & Pin Assignments

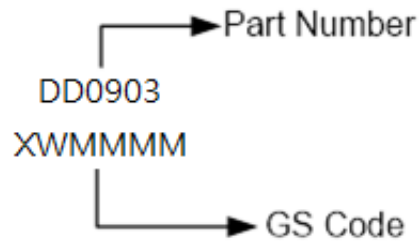
GSMDD0903DF (TO-252-2L)	
 <p>Top View</p>	
Description	
Gate	
Source	
Drain	

Ordering Information



Part Number	Package	Quantity Reel
GSMDD0903DF	TO-252-2L	2500 PCS

Marking Information



Absolute Maximum Ratings

$T_C=25^\circ\text{C}$ Unless otherwise noted

Symbol	Parameter	Typical	Unit
V_{DS}	Drain-Source Voltage	-100	V
V_{GS}	Gate -Source Voltage	± 25	V
I_D	Continuous Drain Current	$T_C=25^\circ\text{C}$	-10
		$T_C=100^\circ\text{C}$	-6.5
I_{DM}	Pulsed Drain Current	-40	A
P_D	Power Dissipation ($T_C=25^\circ\text{C}$)	88	W
	Power Dissipation (Derate above 25°C)	0.59	W/ $^\circ\text{C}$
T_J	Operating Junction Temperature Range	-55 to +150	$^\circ\text{C}$
T_{STG}	Storage Temperature Range	-55 to +150	$^\circ\text{C}$
$R_{\theta JA}$	Thermal Resistance-Junction to Ambient	62	$^\circ\text{C}/\text{W}$
$R_{\theta JC}$	Thermal Resistance-Junction to Case	1.7	$^\circ\text{C}/\text{W}$

Electrical Characteristics

T_J=25°C Unless otherwise noted

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =-250μA	-100			V
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =-250μA	-1		-3	V
I _{GSS}	Gate Leakage Current	V _{DS} =0V, V _{GS} =±25V			±100	nA
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =-100V, V _{GS} =0V			-1	μA
		V _{DS} =-80V, V _{GS} =0V, T _J =125°C			-10	
I _S	Continuous Source Current	V _G =V _D =0V, Force Current			-10	A
I _{SM}	Pulsed Source Current				-20	
R _{DS(on)}	Drain-Source On-Resistance	V _{GS} =-10V, I _D =-6A		115	140	mΩ
		V _{GS} =-4.5V, I _D =-3A		130	170	mΩ
V _{SD}	Diode Forward Voltage	V _{GS} =0V, I _S =-1A			-1.2	V
Dynamic						
Q _g	Total Gate Charge	V _{DS} =-50V, V _{GS} =-10V, I _D =-6A		40.4	70	nC
Q _{gs}	Gate-Source Charge			7.7	15	
Q _{gd}	Gate-Drain Charge			6.6	13	
C _{iss}	Input Capacitance	V _{DS} =-30V, V _{GS} =0V, f=1MHz		2250	3900	pF
C _{oss}	Output Capacitance			130	250	
C _{rss}	Reverse Transfer Capacitance			90	180	
t _{d(on)}	Turn-On Time	V _{DD} =-30V, I _D =-1A, V _{GS} =-10V, R _G =6Ω		27	54	ns
t _r				12	24	
t _{d(off)}	Turn-Off Time			150	300	
t _f				45	90	
R _g	Gate Resistance		V _{DS} =0V, V _{GS} =0V, f=1MHz		10	

Typical Performance Characteristics

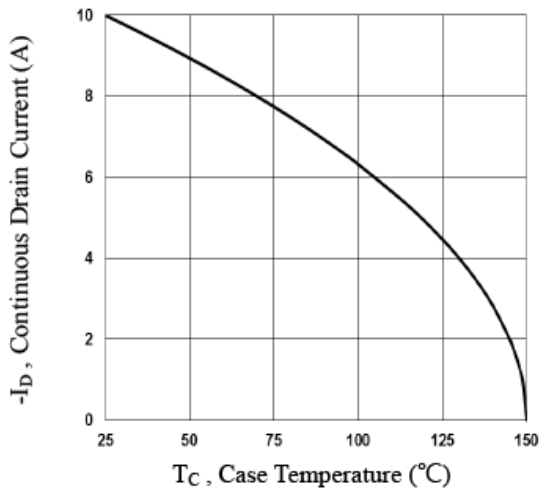


Fig.1 Continuous Drain Current vs. T_c

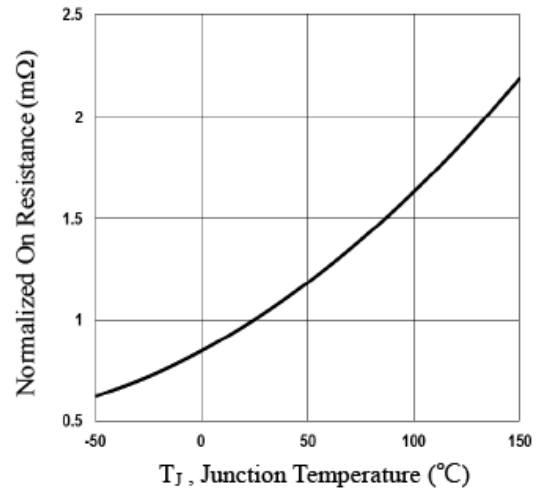


Fig.2 Normalized $R_{DS(on)}$ vs. T_j

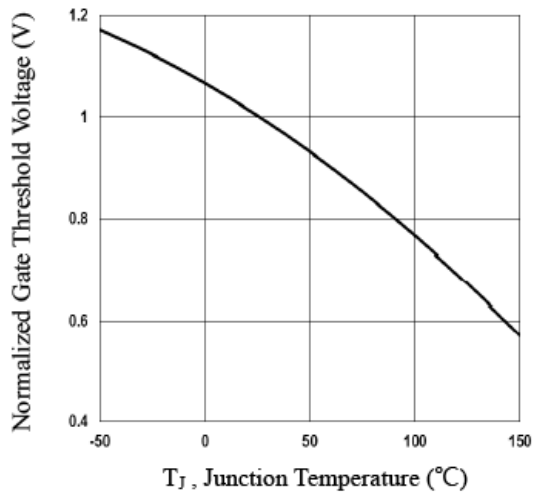


Fig.3 Normalized V_{th} vs. T_j

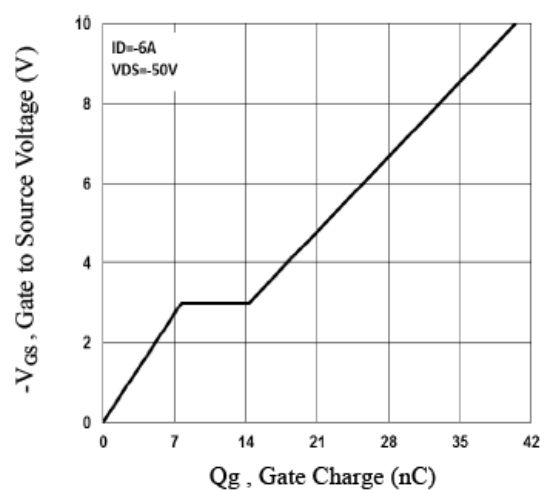


Fig.4 Gate Charge Waveform

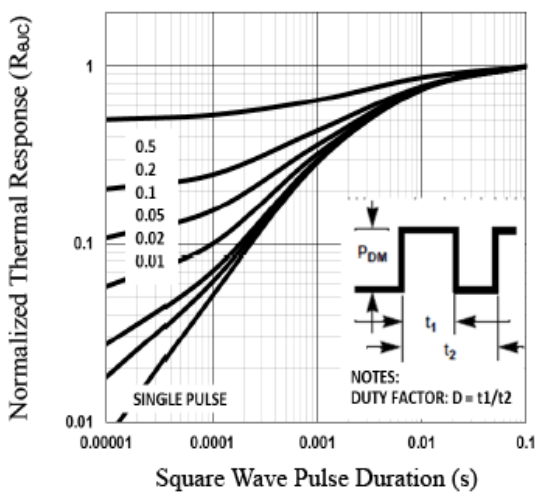


Fig.5 Normalized Transient Impedance

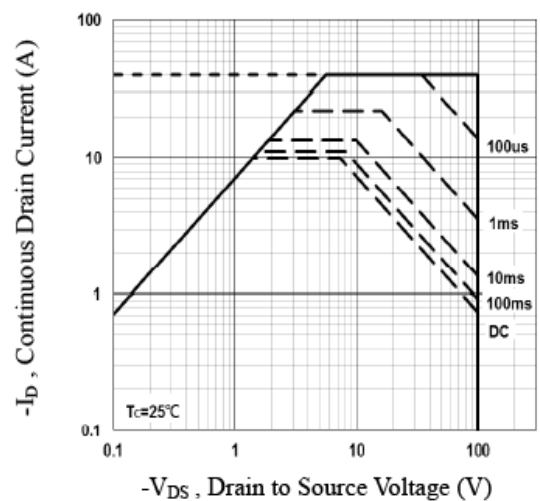
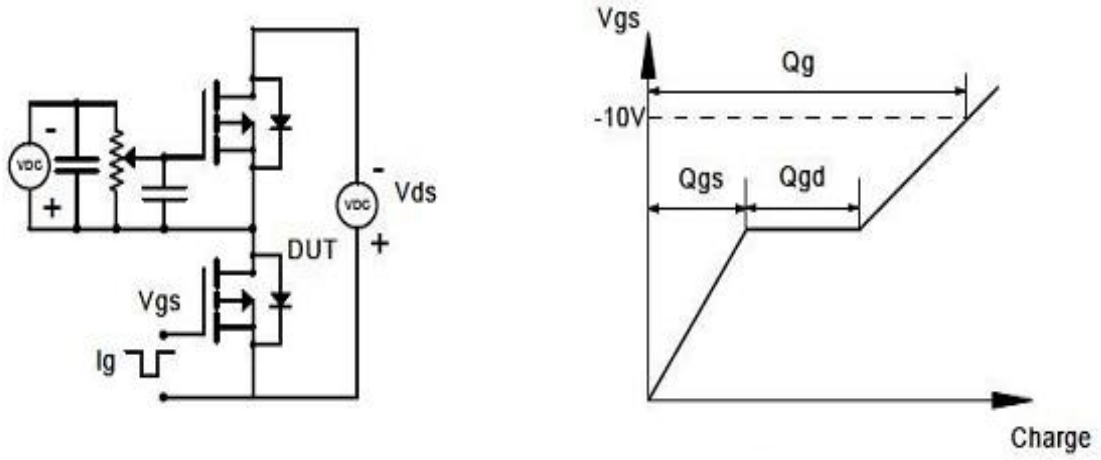


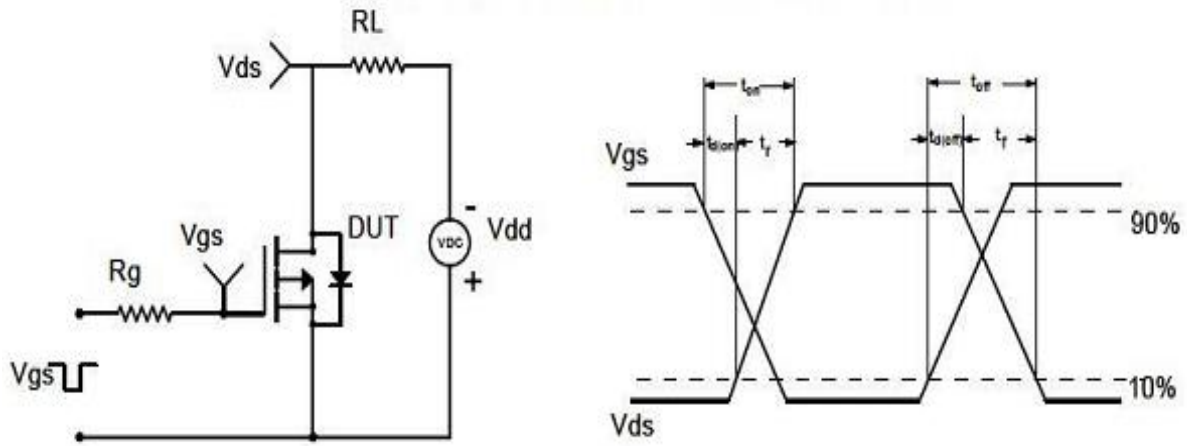
Fig.6 Maximum Safe Operation Area

Typical Performance Characteristics (Continue)

Gate Charge Test Circuit & Waveform

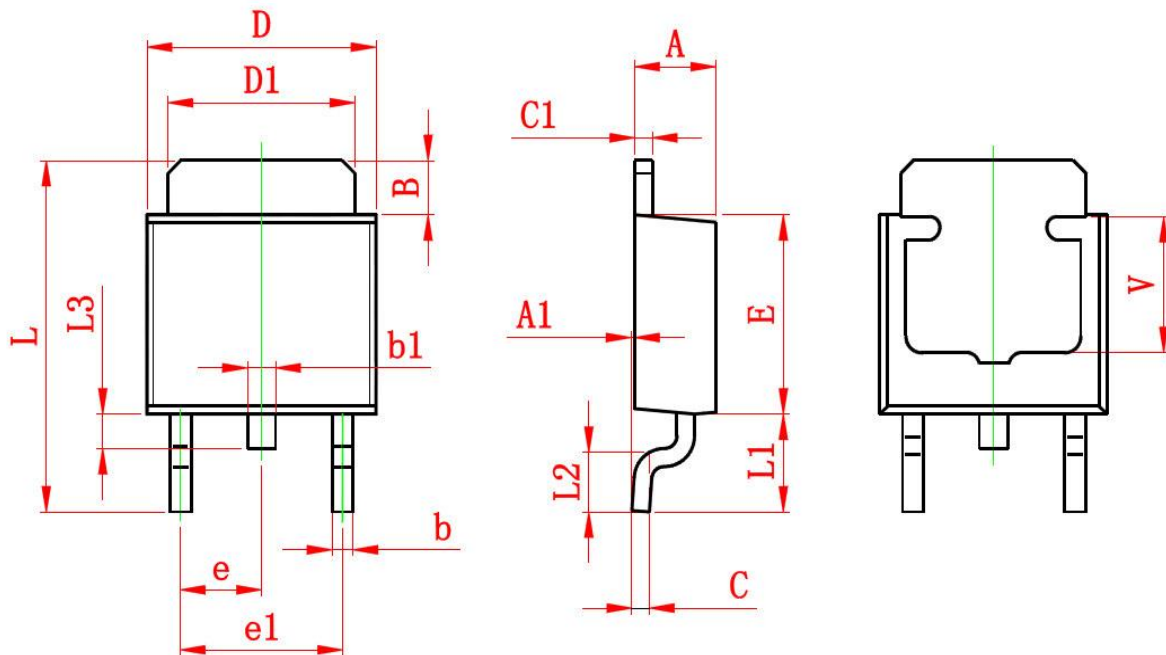


Resistive Switching Test Circuit & Waveforms



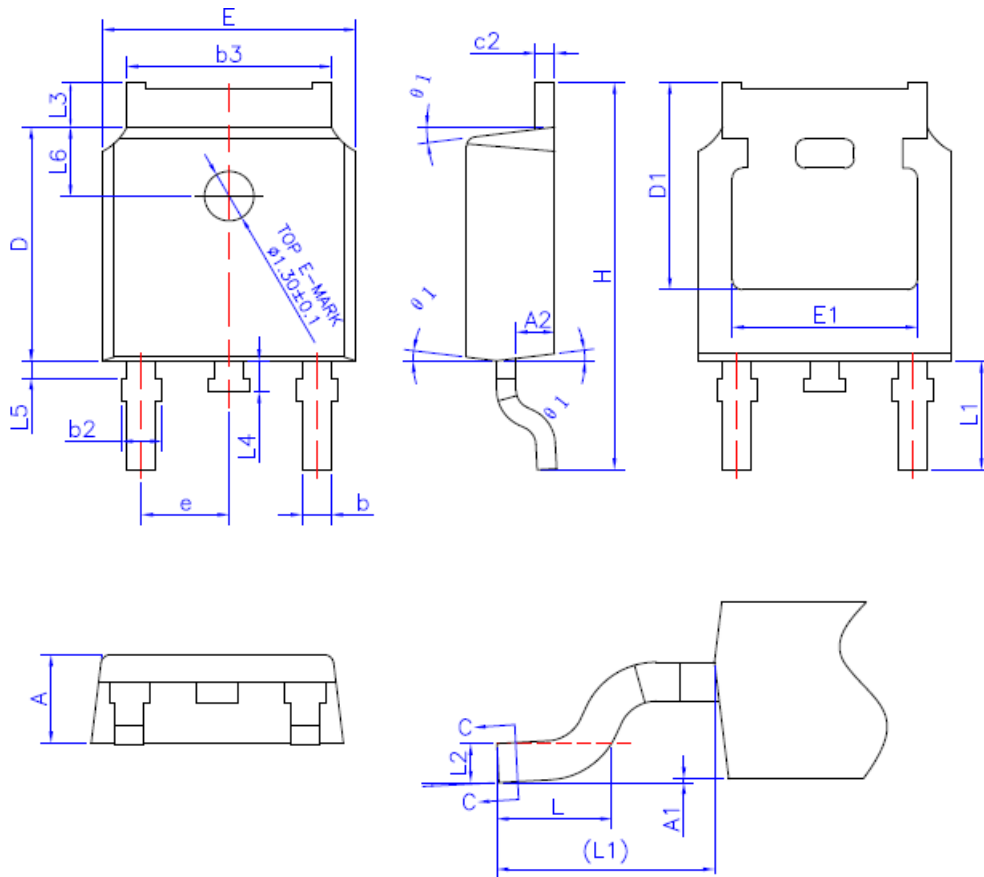
Package Dimension

TO-252-2L PLASTIC PACKAGE



Dimensions

SYMBOL	Millimeters		Inches	
	MIN	MAX	MIN	MAX
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
B	1.350	1.650	0.053	0.065
b	0.500	0.700	0.020	0.028
b1	0.700	0.900	0.028	0.035
c	0.430	0.580	0.017	0.023
c1	0.430	0.580	0.017	0.023
D	6.350	6.650	0.250	0.262
D1	5.200	5.400	0.205	0.213
E	5.400	5.700	0.213	0.224
e	2.300 TYP		0.091 TYP	
e1	4.500	4.700	0.177	0.185
L	9.500	9.900	0.374	0.390
L1	2.550	2.900	0.100	0.114
L2	1.400	1.780	0.055	0.070
L3	0.600	0.900	0.024	0.035
V	3.800 REF		0.150 REF	







Dimensions



SYMBOL	Millimeters		Inches	
	MIN	MAX	MIN	MAX
A	2.200	2.400	0.087	0.094
A1	0.000	0.13	0.000	0.0051
B	0.890	1.270	0.035	0.050
b	0.500	0.880	0.020	0.034
C	0.430	0.580	0.017	0.023
C1	0.430	0.600	0.017	0.024
E	6.350	6.800	0.250	0.268
E1	5.200	5.500	0.205	0.217
D	5.400	6.220	0.213	0.245
e	2.300 REF		0.091 REF	
L	1.400	1.780	0.055	0.070
L1	2.900 REF		0.114 REF	
V	5.250 REF		0.207 REF	
D2	4.443 REF		0.175 REF	

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